

CLAIMS

1           1.    A method of providing thermal connection between a  
2 cooling device and a device to be cooled, the method comprising:

3           a.    applying an adhesive to a thermal interface outside a  
4 heat transfer area of the thermal interface;

5           b.    attaching the thermal interface to the cooling device;  
6 and

7           c.    attaching the device to be cooled to the thermal  
8 interface.

1           2.    The method of claim 1 wherein said adhesive includes a  
2 pressure sensitive adhesive (PSA).

1           3.    The method of claim 1 wherein said cooling device  
2 includes a heat sink device.

1           4.    The method of claim 1 wherein said cooling device  
2 includes a thermal plate.

1           5.    The method of claim 1 wherein said device to be cooled  
2 includes an integrated circuit package.

1           6.    The method of claim 1 wherein said adhesive is applied  
2 at a periphery of said thermal interface.

1           7.    The method of claim 1 wherein said thermal interface  
2 includes a Chomerics T443 film.



4       an adhesive applied to the first surface outside the heat  
5 transfer area;

6        a cooling device attached to the thermal interface at said  
7 first surface thereof; and

8        a device to be cooled attached at said second surface of  
9    the thermal interface.

1        16. The apparatus of claim 15 wherein said adhesive  
2 includes a pressure sensitive adhesive (PSA).

1        17. The apparatus of claim 15 wherein said cooling device  
2 includes a heat sink.

1        18. The apparatus of claim 15 wherein said device to be  
2        cooled includes an integrated circuit package.

1        19. The apparatus of claim 15 wherein said device to be  
2        cooled includes a thermal plate.